

# **Device Modeling Report**

COMPONENTS:MAGNETIC CORE  
PART NUMBER:H5C3  
MANUFACTURER:TDK



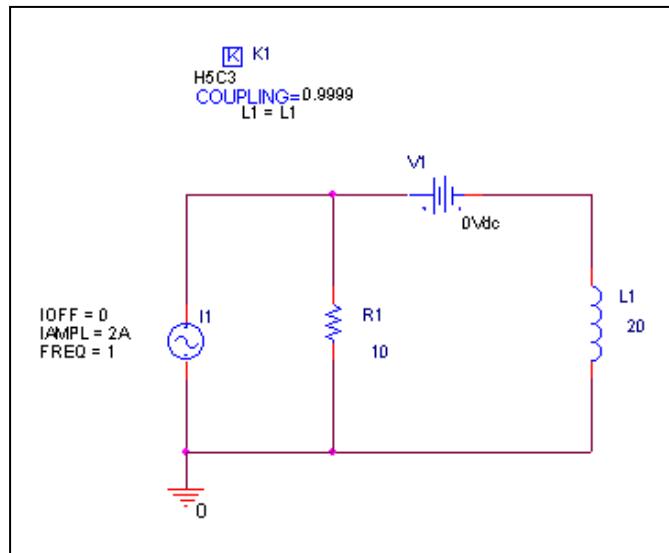
**Bee Technologies Inc.**

## MAGNETIC CORE

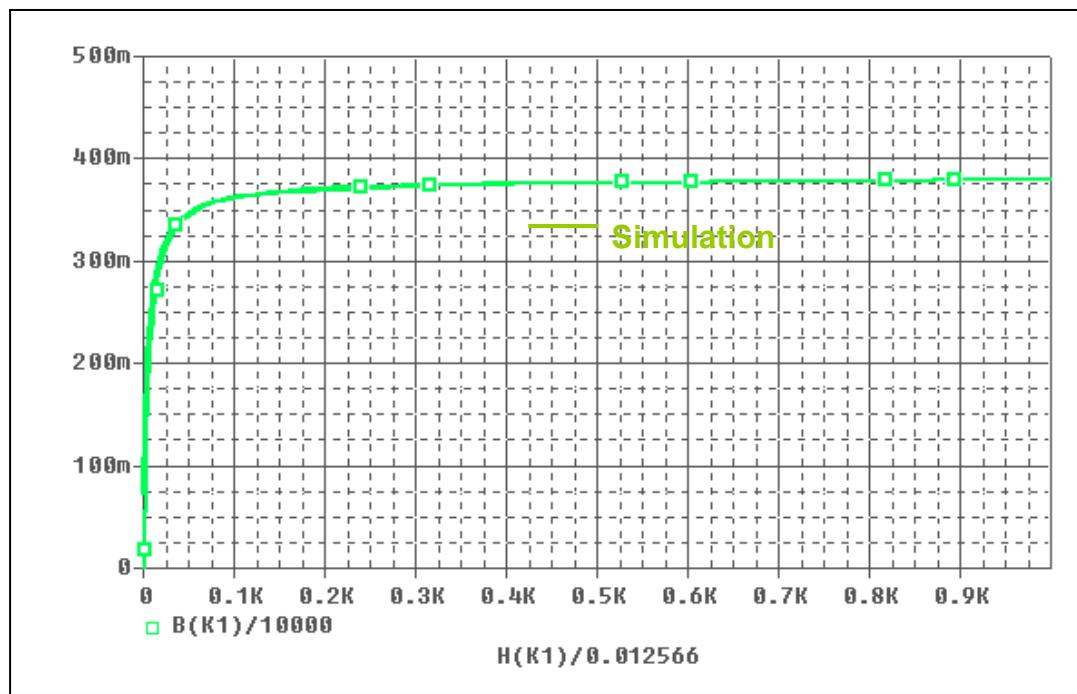
Pspice model parameter	Model description
A	thermal energy parameter
K	domain anisotropy parameter
C	domain flexing parameter
MS	magnetization saturation

## Hysteresis Curve Characteristics

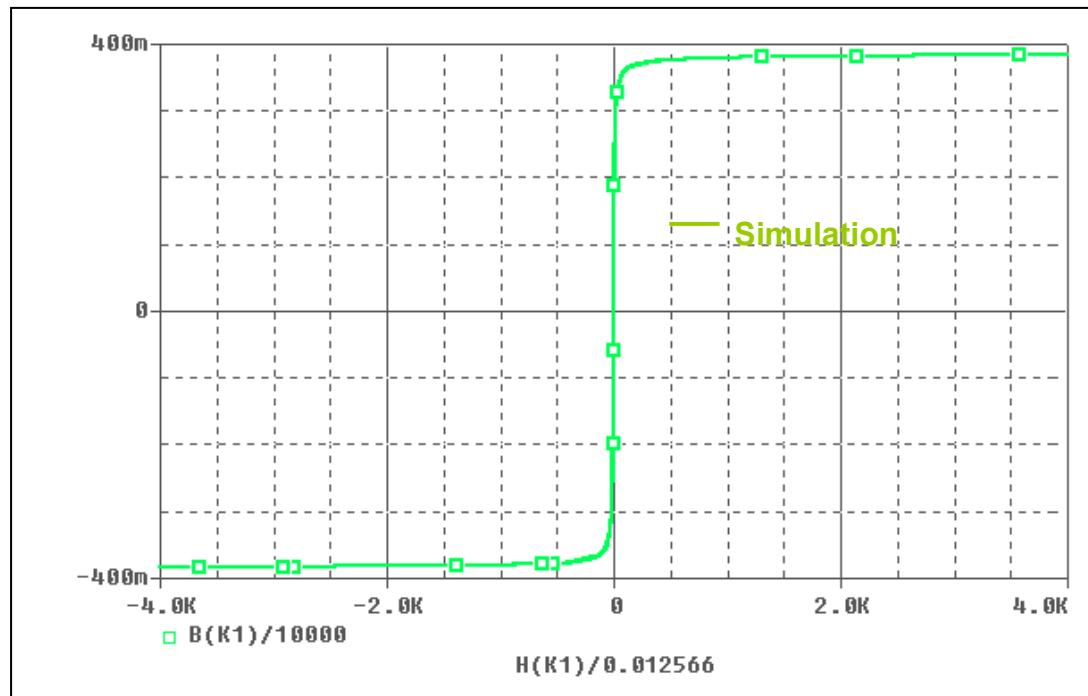
Evaluation Circuit



Simulation result



## Simulation result



**Comparison Table**

H(A/m)	B(mT) Measurement	B(mT) Simulation	%Error
50	350	344.576	1.550
100	365	361.825	0.870
200	370	371	0.270
300	370	374.226	1.142
400	372	375.951	1.062
500	375	376.883	0.502
600	375	377.742	0.731
700	375	378.311	0.883
800	375	378.782	1.009
900	375	379.211	1.123
1000	375	379.53	1.208